Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model
[List multiple models if applicable.]
HP Pavilion Slimline s3600 PC Series

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>0</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>The QTY may vary from different power supply models</td>
<td>2</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at [EL-MF877-01](#)
Components, parts and materials containing refractory ceramic fibers | 0

Components, parts and materials containing radioactive substances | 0

2.0 Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 Phillips screw driver</td>
<td>NO 2</td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove Access Panel from the chassis
2. Take off Front Panel
3. Remove all the cables from PCA
4. Remove PCI & PCI-E card from the PCA
5. Take off Front Panel
6. Remove ODD from the system
7. Remove HDD CAGE from the system
8. Remove the ODD CAGE
9. Remove the Motherboard
10. Take off CMOS battery
11. Take away the Power
12. Open the metallic crust
13. Separate the capacitor

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Screw driver Phillips screw driver NO 2
1. **Remove Access Panel from the chassis**
   Unfasten the 3pcs screws, and take off the Access Panel

2. **take off Front Panel**
   Pull the button up and then take off the front panel

3. **Remove all the cables from PCA**
   Press the button to pull power cords off
   Pull the other cords off PCA

4. **remove PCI & PCI-E card from the PCA**
   Use screw driver to take off the screw as shown in the Photo,take away the slot lock,and then take away the PCI.
5. Remove the Mini_PMD BAY.

Pull the black plastic hander, and take away the Mini_PMD BAY.

6. Remove ODD from the system

Rotate the screw driver to take off the ODD, have the metallic lock pulled by left hand and right hand push ODD out of the base.

7. Remove HDD CAGE from the system

Rotate the screw shown in photo and Remove HDD CAGE from the system

8. Remove the ODD CAGE

Rotate the 3 pcs screws shown in photo and Remove ODD CAGE from the base.
9. *Remove the Motherboard*

Remove 4 pcs screws and take off the Motherboard.

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10. *Take off CMOS battery*

Pull the battery holder as shown in the photo, and then the battery will off the PCA.

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11. *Take away the Power*

Unfasten the 4 pcs screws and take away the Power.

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12. *Open the metallic crust*

Unfasten the 5 pcs screws and open the metallic crust.
13. Separate the capacitor

use screw driver to separate the capacitor from the main board of power.